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each of said mask patterns respectively prepared for said plural circuit elements has a mark for positioning, and positioning of said mask patterns is performed by superposing one of said marks on another of said marks.

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23. A semiconductor device manufactured by the method according to Claim 21.

24. A semiconductor device manufactured by the method according to Claim 22.--

REMARKS

Favorable consideration of this application as presently amended and in light of the following discussion is respectfully requested.

Claims 1-20 canceled, and Claims 21-24 added by way of the present preliminary amendment. Claims 21-24 correspond to non-elected claims 51-54 of the parent application and therefore addition of these claims is not believed to raise a question of new matter.

Accordingly, examination in the merits is believed to be in order and an early and favorable action is respectfully requested.

Respectfully submitted,

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